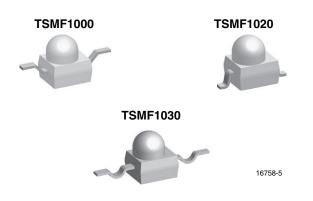
Vishay Semiconductors

High Speed Infrared Emitting Diode, RoHS-Compliant, 890 nm, Surface Emitter Technology



www.vishay.com

DESCRIPTION

TSMF1000 series are infrared, 890 nm emitting diodes based on surface emitter chip technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

FEATURES

- Package type: surface-mount
- · Package form: GW, RGW, yoke
- Dimensions (L x W x H in mm): 2.5 x 2 x 2.7
- Peak wavelength: λ_p = 890 nm
- High radiant power
- Angle of half intensity: $\varphi = \pm 11^{\circ}$
- · Low forward voltage
- Suitable for high pulse current operation
- Package matches with detector TEMD1000
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- · Control and drive circuits
- Shaft encoders

PRODUCT SUMMARY				
COMPONENT	l _e (mW/sr)	φ (°)	λ _P (nm)	t _r (ns)
TSMF1000	27	± 11	890	15
TSMF1020	27	± 11	890	15
TSMF1030	27	± 11	890	15

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
TSMF1000	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing	
TSMF1020	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing	
TSMF1030	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Yoke	

Note

MOQ: minimum order quantity





COMPLIANT



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ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	5	V	
Forward current		I _F	100	mA	
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I _{FM}	200	mA	
Surge forward current	t _p = 100 μs	I _{FSM}	1	A	
Power dissipation		Pv	190	mW	
Junction temperature		Tj	100	°C	
Ambient temperature range		T _{amb}	-40 to +85	°C	
Storage temperature range		T _{stg}	-40 to +100	°C	
Soldering temperature	t ≤ 5 s	T _{sd}	260	°C	
Thermal resistance junction to ambient	JESD51	R _{thJA}	250	K/W	

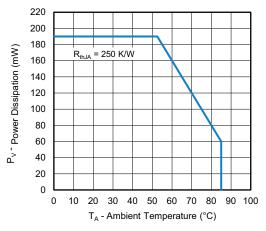


Fig. 1 - Power Dissipation vs. Ambient Temperature

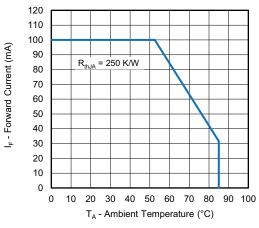


Fig. 2 - Forward Current vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 20 mA	V _F	-	1.3	1.5	V
	$I_F = 100 \text{ mA}, t_p = 100 \mu\text{s}$	V _F	-	1.5	-	V
	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	V _F	-	2.6	-	V
Temperature coefficient of V _F	I _F = 20 mA	TK _{VF}	-	-1.4	-	mV/K
Reverse current		I _R	Not designed for reverse operation µA			μA
Junction capacitance	V _R = 0 V, f = 1 MHz, E = 0	Cj	-	56	-	pF
	I _F = 20 mA	l _e	15	27	40	mW/sr
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 100 \mu\text{s}$	le	l _e - 15	155	-	mW/sr
Radiant power	I _F = 20 mA, t _p = 20 ms	фе	-	10	-	mW
Temperature coefficient of ϕ_{e}	I _F = 20 mA	ΤKφ _e	-	-0.3	-	%/K
Angle of half intensity		φ	-	± 11	-	0
Peak wavelength	I _F = 20 mA	λρ	-	890	-	nm
Spectral bandwidth	I _F = 20 mA	Δλ	-	35	-	nm
Temperature coefficient of λ_p	I _F = 20 mA	ΤΚλ _ρ	-	0.3	-	nm/K
Rise time	I _F = 20 mA	t _r	-	15	-	ns
Fall time	I _F = 20 mA	t _f	-	15	-	ns

2



100

90

80

700

I_F = 20 mA

750

0.4

0.6

0.2

0

Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

800

λ - Wavelength (nm)

Fig. 6 - Relative Radiant Intensity vs. Wavelength

0

850

10°

900

20°

950

30°

40°

50°

60°

70° 80° φ - Angular Displacement

 $I_{\rm e, \ rel.}$ - Relative Radiant Intensity (%)

l_{e, rel.} - Relative Radiant Intensity

1.0 0.9

0.8

0.7

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BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

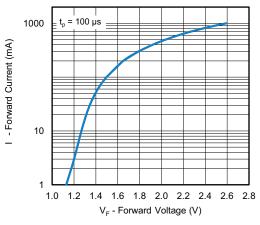


Fig. 3 - Forward Current vs. Forward Voltage

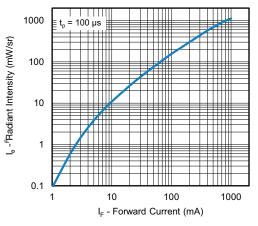


Fig. 4 - Radiant Intensity vs. Forward Current

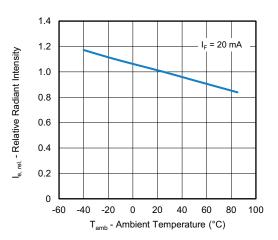


Fig. 5 - Relative Radiant Intensity vs. Ambient Temperature

3



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PRECAUTIONS FOR USE

1. Over-Current-Proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (burn out will happen).

2. Storage

- \bullet Storage temperature and rel. humidity conditions are: 5 °C to 35 °C, R.H. 60 %.
- Floor life must not exceed 168 h, according to JEDEC[®] level 3, J-STD-020.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccant.

Considering tape life, we suggest to use products within one year from production date.

- If opened more than one week in an atmosphere 5 °C to 35 °C, R.H. 60 %, devices should be treated at 60 °C \pm 5 °C for 15 h.
- If humidity indicator in the package shows pink color (normal blue), then devices should be treated with the same conditions as 2.3.

REFLOW SOLDER PROFILE

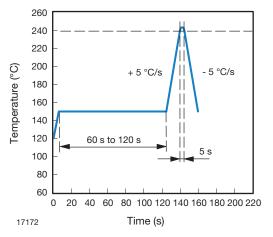
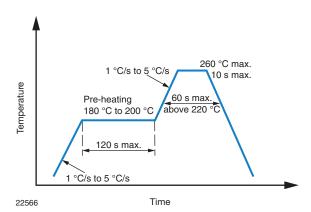
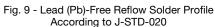


Fig. 8 - Lead Tin (SnPb) Reflow Solder Profile

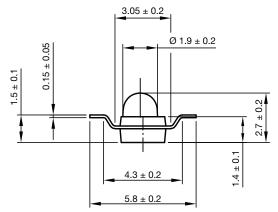


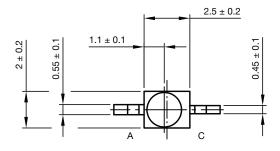




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PACKAGE DIMENSIONS in millimeters: TSMF1000





4 ± 0.2

 0.3 ± 0.1

-

С

 2.5 ± 0.2

 0.45 ± 0.1

Ø 1.9 ± 0.2

Ζ

Drawing-No.: 6.544-5326.03-4 Issue: 1; 15.09.2021

0.83 ± 0.1

 0.55 ± 0.1

 2 ± 0.2

PACKAGE DIMENSIONS in millimeters: TSMF1020

 0.15 ± 0.05

Π

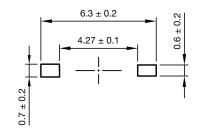
А

 1.1 ± 0.1

Drawing-No.: 6.544-5325.03-4 Issue: 1; 15.09.2021

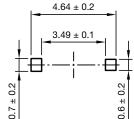
Technical drawings according to DIN specifications

Solder pad proposal



Technical drawings according to DIN specifications

Solder pad proposal



 2.7 ± 0.2

1.4 ± 0.1

Z 10:1

Max. 0.13

 0.75 ± 0.1

Rev. 1.9, 22-Oct-2021

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Document Number: 81061

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Technical drawings according to DIN

specifications

Solder pad proposal

 7.9 ± 0.2

 5.49 ± 0.1

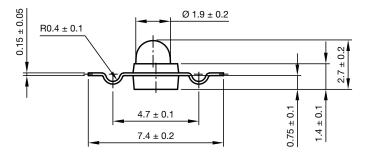
 0.7 ± 0.2

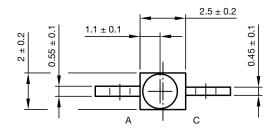


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 0.6 ± 0.2

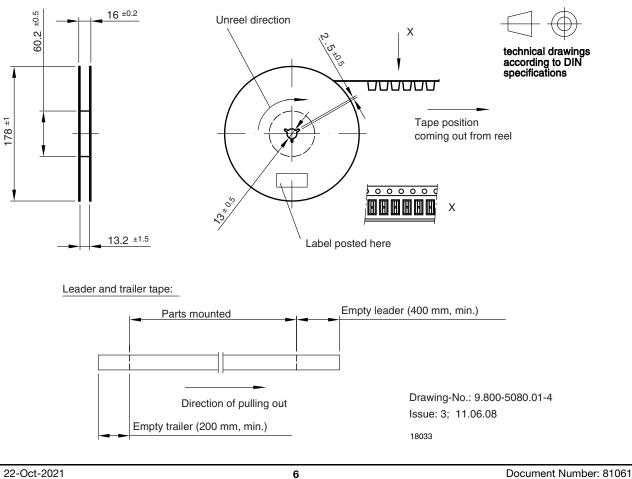
PACKAGE DIMENSIONS in millimeters: TSMF1030





Drawing-No.: 6.544-5329.03-4 Issue: 1; 15.09.2021





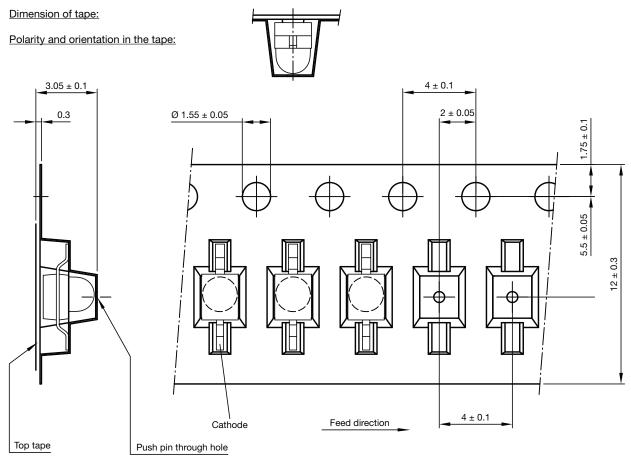
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TAPING DIMENSIONS in millimeters: TSMF1000



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5268.02-4 Issue: 1; 28.09.2021

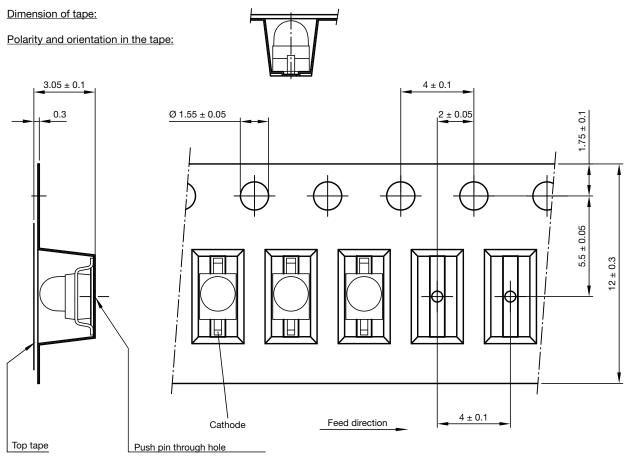


Technical drawings according to DIN specifications



Vishay Semiconductors

TAPING DIMENSIONS in millimeters: TSMF1020



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5269.02-4 Issue: 1; 28.09.2021

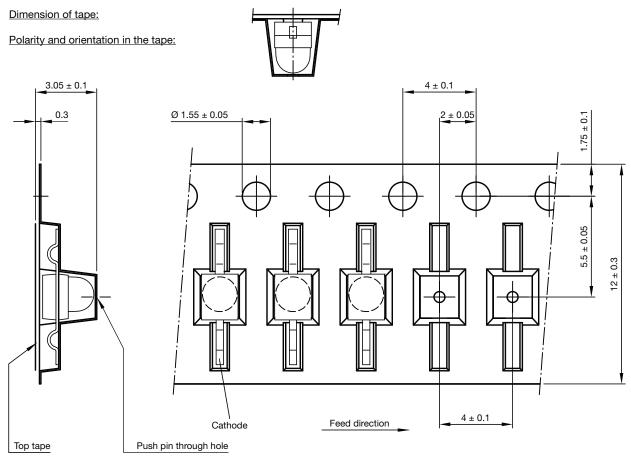


Technical drawings according to DIN specifications



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TAPING DIMENSIONS in millimeters: TSMF1030



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5270.02-4 Issue: 1; 28.09.2021



Technical drawings according to DIN specifications



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